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(71) Applicant *(for all designated States except US)*: **KULICKE & SOFFA INVESTMENTS, INC.** [US/US]; Little Falls Center Two, Suite 3165, 2571 Centerville Road, Wilmington, DE 19808 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **BATISH, Rakesh** [US/US]; 189 Abbey Drive, Royersford, PA 19468 (US). **KULICKE, C., Scott** [US/US]; 6112 Sheaff Lane, Fort Washington, PA 19034 (US). **HMIEL, Andrew, F.** [US/US]; 2150 Wharton Drive, Glenside, PA 19038 (US). **VONSEGGERN, Walt** [US/US]; 1936 Street Road, New Hope, PA 18938 (US).

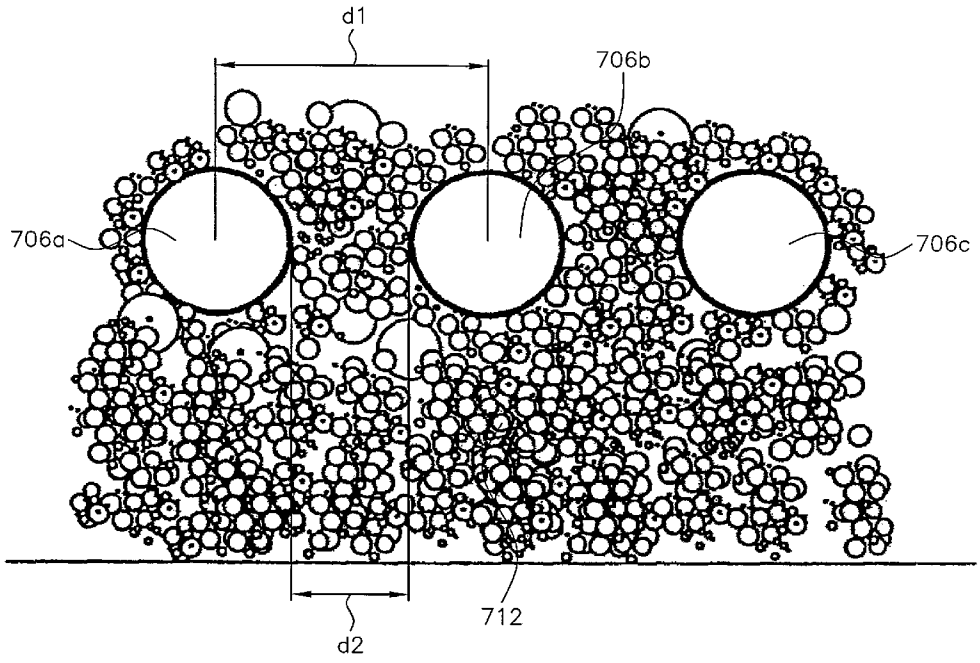
(74) Agent: **ETKOWICZ, Jacques, L.**; RatnerPrestia, P.O. Box 980, Valley Forge, PA 19482 (US).

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(54) Title: SYSTEM AND METHOD FOR PREVENTING AND ALLEVIATING SHORT CIRCUITING IN A SEMICONDUCTOR DEVICE



(57) Abstract: A method of packaging a semiconductor device including a plurality of elements is provided. The method includes applying an insulative material to at least a portion of the semiconductor device, where the insulative material includes insulative particles having a diameter smaller than a gap between adjacent conductors providing interconnection between the elements. The method also includes curing the insulative material.

WO 2005/041299 A1

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